

LISTING OF THE CLAIMS

1. (Previously Presented) A device, comprising:
a leadframe body having leads, wherein the lead frame body is of a lead-on-chip (LOC) type;
a plurality of inner leads formed in the leadframe body; and
a locking tape adhered to tips of the plurality of inner leads, the locking tape being cut together with the inner leads.
2. (Original) The device according to claim 1, wherein the inner leads are made using a stamping process.
3. (Canceled)
4. (Original) The device according to claim 1, wherein the locking tape is double-sided tape which has an adhesive on both sides thereof.
5. (Original) The device according to claim 1, wherein the locking tape is one-sided tape having an adhesive on only one side thereof, the side having adhesive being adhered to the inner leads.
6. (Withdrawn) A method, comprising:
performing a stamping process for forming inner leads in a leadframe member;
adhering locking tape to tips of the inner leads; and

simultaneously cutting the inner lead tips and the locking tape.

7. (Withdrawn) The method of claim 6, wherein the leadframe is a LOC type.
8. (Withdrawn) The method of claim 6, wherein the locking tape is double-sided tape which has an adhesive on both sides thereof.
9. (Withdrawn) The method of claim 6, wherein the locking tape is one-sided tape having an adhesive on only one side thereof, the adhesive being adhered to the inner leads.
10. (Withdrawn) The method of claim 6, wherein the simultaneous cutting of the inner lead tips and the locking tape is performed using one punch.
11. (Original) A device, comprising:
a leadframe body including a plurality of leads, wherein the leadframe body is of a lead-on-chip (LOC) type; and
tape adhered to the plurality of leads, the tape ending at an end of each of the plurality of leads.
12. (Original) The device according to claim 11, wherein the tape is double sided tape having adhesive on both sides thereof.
13. (Original) The device according to claim 11, wherein the tape is single sided tape having adhesive on only one side thereof.

14. (Canceled)

15. (Original) The device according to claim 13, wherein the leadframe body is a general stamped leadframe.

16. (Withdrawn) A method, comprising:
adhering tape to leads of a leadframe; and
cutting the tape and a portion of the leads simultaneously, the cutting of the tape resulting in an edge of the tape being defined along tips of the leads.

17. (Withdrawn) The method according to claim 16, wherein the tape is double sided tape having adhesive on both sides thereof.

18. (Withdrawn) The method according to claim 16, wherein the tape is single sided tape having adhesive on both sides thereof.

19. (Withdrawn) The method according to claim 17, wherein the leadframe body is a LOC type stamped leadframe.

20. (Withdrawn) The method according to claim 18, wherein the leadframe body is a general stamped leadframe.